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(71) Applicant:  
Hewlett-Packard Company  
Palo Alto, California 94304 (US)

(72) Inventors:

- Humphrey, Guy H.  
Q83, Ft. Collins, CO 80525 (US)
- Fisher, Rory L.  
Ft. Collins, CO 80525 (US)
- D'Amato, Jerry  
Loveland, CO 80537 (US)

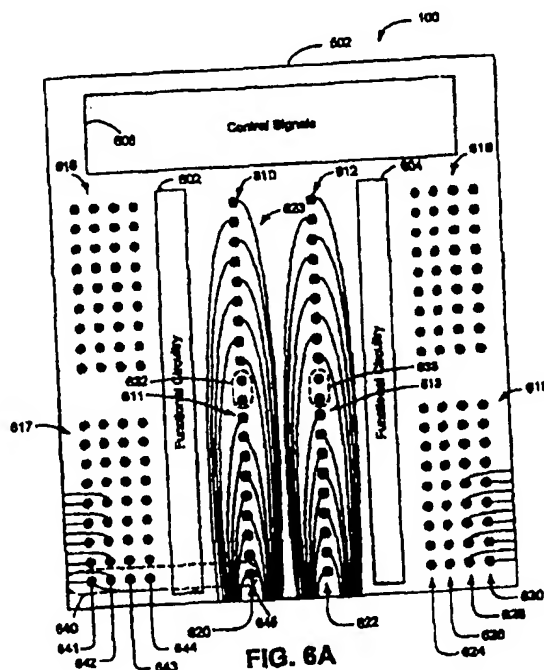
(74) Representative:

Schoppe, Fritz, Dipl.-Ing.  
Schoppe, Zimmermann & Stöckeler  
Patentanwälte  
Postfach 71 08 67  
81458 München (DE)

### (54) Integrated circuit having unique lead configuration

(57) The present invention is generally directed to an integrated circuit package (100) having a unique lead configuration, wherein the integrated circuit package is constructed from a die (502) containing an integrated circuit. The die (502) has a plurality of leads (504) for carrying electrical signals to and from the integrated circuit, wherein the plurality of leads are disposed over a bottom side of the die (502). The package further includes a multi-layer substrate (506) having at least two signal layers. The substrate (506) is juxtaposed against the die (502) and has a plurality of contacts (507) disposed along a top side to align with the leads (504) of the die to carry the electrical signals to conductive paths within the at least two signal layers. The multi-layer substrate has a larger adjoining surface area than the die and further has a plurality of leads (520) disposed across a bottom side for connection with a printed circuit board (508), the on the bottom side being in communication with the leads of the top side by way of the conductive paths disposed within the substrate. The leads (504) of the die (502) are disposed such that at least two high speed rows (620, 622) of leads are disposed in parallel fashion near the center of the die (502), wherein the high speed rows (620, 622) are for carrying high frequency electrical signals. At least two sets (617, 619) of low speed rows of leads are disposed in parallel fashion near the sides of the die, and spaced apart from the

high speed rows.



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## EUROPEAN SEARCH REPORT

Application Number  
EP 99 10 1126

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The present search report has been drawn up for all claims			
Place of search BERLIN		Date of completion of the search 10 March 2000	Examiner Le Meur, M-A
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# ANNEX TO THE EUROPEAN SEARCH REPORT ON EUROPEAN PATENT APPLICATION NO.

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